

# PATENT ASSIGNMENT

Electronic Version v1.1  
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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Huang Soon Kang</td> <td>07/01/2010</td> </tr> <tr> <td>Han-Hsin Kuo</td> <td>07/01/2010</td> </tr> <tr> <td>Chi-Ming Yang</td> <td>07/01/2010</td> </tr> <tr> <td>Shwang-Ming Jeng</td> <td>07/02/2010</td> </tr> <tr> <td>Chin-Hsiang Lin</td> <td>07/02/2010</td> </tr> </tbody> </table>		Name	Execution Date	Huang Soon Kang	07/01/2010	Han-Hsin Kuo	07/01/2010	Chi-Ming Yang	07/01/2010	Shwang-Ming Jeng	07/02/2010	Chin-Hsiang Lin	07/02/2010
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd., 6, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD	Street Address:	No. 8, Li-Hsin Rd., 6, Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77		
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<b>PROPERTY NUMBERS Total: 1</b>													
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (214)200-0853  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 972-739-8631</p> <p>Email: saadia.cooks@haynesboone.com</p> <p>Correspondent Name: Rachel Davis</p> <p>Address Line 1: 2323 Victory Avenue, Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.1489												
NAME OF SUBMITTER:	Rachel Davis												

CH \$40.00 12829664

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**PATENT**  
**REEL: 024919 FRAME: 0772**

Total Attachments: 3

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Docket No.: 2010-0368 / 24061.1489  
Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- |     |                  |    |   |
|-----|------------------|----|---|
| (1) | Huang Soon Kang  | of | 40-1, Alley 14, Lane 452, Bao San Road<br>Hsin-Chu, Taiwan, R.O.C.                |
| (2) | Han-Hsin Kuo     | of | No. 85, Sec. 2, Jhinghua S. Road, South District<br>Tainan City, Taiwan, R.O.C.   |
| (3) | Chi-Ming Yang    | of | 4, Lane 67, Duan-Feng Road, Hsian-San District<br>Hsin-Chu 300-77, Taiwan, R.O.C. |
| (4) | Shwang-Ming Jeng | of | 9F, No. 19, 22nd Alley, Nan-Chung Street<br>Hsin-Chu, Taiwan, R.O.C.              |
| (5) | Chin-Hsiang Lin  | of | No. 37, Lane 393, Min-Hu Road<br>Hsin-Chu, Taiwan, R.O.C.                         |

have invented certain improvements in

### METAL CONDUCTOR CHEMICAL MECHANICAL POLISH

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
  X   filed on July 2, 2010 and assigned application number 12/829,664 ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

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invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Huang Soon Kang

Residence Address: 40-1, Alley 14, Lane 452, Bao San Road  
Hsin-Chu, Taiwan, R.O.C.

Dated: July 1, 2010

Huang Soon Kang  
Inventor Signature

Inventor Name: Han-Hsin Kuo

Residence Address: No. 85, Sec. 2, Jhinghua S. Road, South District  
Tainan City, Taiwan, R.O.C.

Dated: July 1, 2010

Han-Hsin Kuo  
Inventor Signature

Inventor Name: Chi-Ming Yang

Residence Address: 4, Lane 67, Duan-Feng Road, Hsian-San District  
Hsin-Chu 300-77, Taiwan, R.O.C.


Dated: July 1, 2010

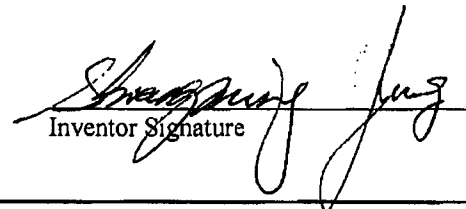
Chi-Ming Yang  
Inventor Signature

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Inventor Name: Shwang-Ming Jeng

Residence Address: 9F, No. 19, 22nd Alley, Nan-Chung Street  
Hsin-Chu, Taiwan, R.O.C.

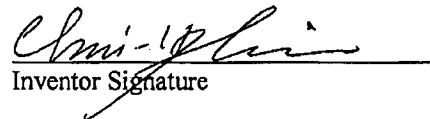
Dated:  7/2/2010

  
Inventor Signature

Inventor Name: Chin-Hsiang Lin

Residence Address: No. 37, Lane 393, Min-Hu Road  
Hsin-Chu, Taiwan, R.O.C.

Dated: 7/2/2010

  
Inventor Signature